

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	55145	(chip and (pad or pads) and (wire or wiring))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 08:51
S2	481	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 09:02
S3	12508	ic adj package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:26
S5	2629	S3 and (spacer or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:27
S6	305	S5 and elastic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:13
S7	24420	ball adj grid adj array or bga	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:29
S8	191	S3 and S6 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:29
S10	16	TOMIMATSU-HIROYUKI	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:43

S13	3	"2001060657"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:44
S14	2	"08088316"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:45
S15	2	"2001308262"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:46
S17	1	"2001514449"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:47
S18	3	"2000058743"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:48
S19	2	"2002222913"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:49
S20	3	"08288455"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:50
S21	5	"2004006670"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:51

S22	7	"9910925"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:51
S23	481	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 13:30
S24	265	S23 and (spacer or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:56
S29	308	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin) and (bump or bumps))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:10
S30	2	"20030057539"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:10
S31	482	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:57
S32	88	S31 and (spacer or ball) and parallel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:57
S33	99	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin) and (bump or bumps) and (parallel))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 13:31
S35	2537	257/777	USPAT	OR	OFF	2005/08/31 12:49